

PRESS STATEMENT/ SIARAN AKHBAR

(FOR IMMEDIATE RELEASE)

**OXFORD INNOTECH DELIVERS RM36.6 MILLION
REVENUE FOR 1HFY25**

- *To ride on global semiconductor growth and opportunities under Malaysia's
13MP*

Kuala Lumpur, 22 August 2025 – Integrated engineering solutions provider, Oxford Innotech Berhad (“OXB” or the “Group”) (牛津科创有限公司), has today announced its second quarter (“2QFY25”) and first half (“1HFY25”) financial results for the period ended 30 June 2025. There are no comparative figures for the preceding corresponding quarter and year-to-date results as this is the second interim financial result being announced in compliance with the ACE Market Listing Requirements of Bursa Malaysia Securities Berhad (“Bursa Malaysia”).

OXB posted revenue of RM17.1 million in 2QFY25, with contribution coming from mechanical assembly solutions segment at RM10.2 million (59.7%), precision engineering components solutions segment (RM6.3 million or 37.0%), while automation and robotics solutions segment made up the balance RM0.6 million or 3.3% of turnover.

Geographically, Malaysia accounted for 93.0% of 2QFY25 revenue, where the Group primarily serves multinational companies with operations in the country. Asia ex-Malaysia contributed 4.7%, with the balance coming from North America and Europe.

Profitability-wise, 2QFY25 profit after tax (“PAT”) stood at RM1.6 million. The results included an one-off listing expenses of approximately RM0.4 million. Excluding this, the Group delivered a normalised PAT of RM2.0 million, translating into a normalised PAT margin of 11.8%.

For 1HFY25, OXB achieved a revenue of RM36.6 million, with a reported PAT of RM4.8 million. Excluding the one-off listing expenses, normalised PAT was RM5.3

million, yielding a normalised PAT margin of 14.4%. The Group also generated a positive net operating cash flow of RM10.9 million in 1HFY25.

Managing Director of OXB, Mr. Ng Thean Gin (黄天仁), commented, “Our 1HFY25 results thus far in FY25 have been within our expectations, and we anticipate activities to pick up pace in the second half of the fiscal year. We are in active discussions on several prospective projects across semiconductor and modular building systems (“MBS”) industries. We look forward to sharing some positive news in due course.”

“Operationally, our team is currently in the testing and commissioning stage at the Phase 1 of our Penang Science Park (“PSP”) Factory 2, with trial production expected to commence in the third quarter of 2025. This new facility has a manufacturing area of 39,392 square feet (“sqft”), bringing our total manufacturing floor space to 125,174 sqft.”

“On the broader market outlook, we remain mindful of the global uncertainties, including the United States (“US”) reciprocal tariffs. Fortunately, the Group’s direct exposure to the US remains minimal and has not impacted our orders. Overall, we remain cautiously positive on the prospect of the key industries we serve, primary semiconductor, electronics and electrical (“E&E”), automotive and MBS.”

Mr. Ng further added, “In fact, under the recently unveiled 13th Malaysia Plan (2026–2030), Malaysia aims to achieve E&E exports of RM1.0 trillion by 2030, up from RM601.0 billion in 2024. This ambitious target is supported by the National Semiconductor Strategy, which includes RM25.0 billion in fiscal support to strengthen key areas of the semiconductor ecosystem. This spells great opportunities ahead for companies like us, and we are well-positioned to capitalise on this growth in the coming years.”

To meet the expected growing demand for its solutions and services, OXB plans to construct another new facility under Phase 2 of PSP Factory 2. Upon completion, the total production space will expand from 125,174 sqft to 192,896 sqft.

To recap, OXB was listed on the ACE Market of Bursa Malaysia on 29 July 2025, successfully raising a total of RM41.6 million, with the bulk of proceeds to be utilised towards expansion of capacity and capabilities.

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About Oxford Innotech Berhad

Headquartered in Penang, Oxford Innotech Berhad (“**OXB**”) (stock code: OXB/0368), through its subsidiaries, is an integrated engineering solutions provider specialising in precision engineering components solutions, mechanical assembly solutions, and automation and robotic solutions. OXB’s customers comprise primarily multinational and local manufacturers and assemblers across various industries, including semiconductor, electrical and electronics, automotive, and modular building systems.

For more information, please visit <https://oxfordinnotech.com/>

Released on behalf of Oxford Innotech Berhad by Capital Front Investor Relations.

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